



### 20V N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON) max</sub>	I <sub>D max</sub> T <sub>A</sub> = +25°C
20V	$9.5 \text{m}\Omega @ V_{GS} = 4.5 \text{V}$	11.7A
200	$11m\Omega$ @ $V_{GS} = 2.5V$	10.8A

### **Description**

This new generation MOSFET is designed to minimize the on-state resistance ( $R_{DS(ON)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### **Applications**

- · General Purpose Interfacing Switch
- Power Management Functions

### **Features**

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Low On-Resistance
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

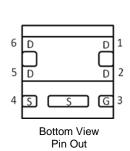
### **Mechanical Data**

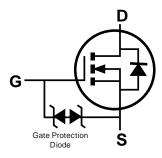
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.0065 grams (Approximate)





**Bottom View** 





**Equivalent Circuit** 

### **Ordering Information** (Note 4)

Part Number Marking		Reel size (inches)	Quantity per reel
DMN2011UFDE-7	N3	7	3,000
DMN2011UFDE-13	N3	13	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



N3 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	201	1	2012		2013	20	14	2015		2016		2017
Code	Υ		Z		Α	[	3	С		D		Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V <sub>DSS</sub>	20	V		
Gate-Source Voltage			$V_{GSS}$	±12	V
Continuous Drain Current (Note C) V 4 5V	I <sub>D</sub>	11.7 9.3	А		
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	14.2 11.4	А
Steady $T_A = +25^{\circ}$ C State $T_A = +70^{\circ}$ C			I <sub>D</sub>	10.8 8.7	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = 2.5V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	13.2 10.6	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	80	Α		
Maximum Body Diode Continuous Current	I <sub>S</sub>	2.5	Α		
Avalanche Current (Note 7) L = 0.1mH	I <sub>AS</sub>	18	А		
Avalanche Energy (Note 7) L = 0.1mH	E <sub>AS</sub>	17	mJ		

## **Thermal Characteristics**

Characteristic	Symbol	Value	Units		
Total Dawer Dissination (Note E)	T <sub>A</sub> = +25°C	6	0.61	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	$P_{D}$	0.39	VV	
Thormal Posistance, Junation to Ambient (Note 5)	Steady state	D	209	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	142		
Total Dawer Dissinction (Note 6)	T <sub>A</sub> = +25°C	6	1.97	w °C/W	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +70°C	$P_{D}$	1.27		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D	64		
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{ hetaJA}$	43		
Thermal Resistance, Junction to Case (Note 6)	_	R <sub>0</sub> JC	9.8		
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C		

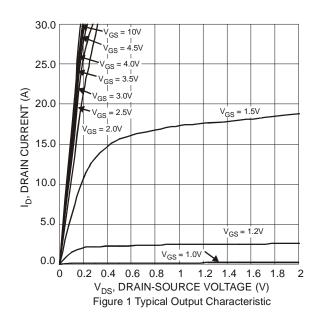


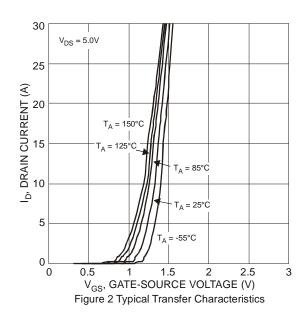
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	1	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_		1	μΑ	$V_{DS} = 16V$ , $V_{GS} = 0V$
Zero Gate Voltage Drain Current T <sub>J</sub> = +150°C (Note 9)	I <sub>DSS</sub>	_		100	μΑ	$V_{DS} = 16V$ , $V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_		±10	μΑ	$V_{GS} = \pm 10V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(th)}$	0.4		1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
			6.5	9.5		$V_{GS} = 4.5V, I_D = 7A$
Static Drain-Source On-Resistance	D-scars		7.5	11	mΩ	$V_{GS} = 2.5V, I_D = 7A$
Static Dialif-Source Off-Resistance	R <sub>DS(ON)</sub>	_	10	20	11152	$V_{GS} = 1.8V, I_D = 5A$
			15	35		$V_{GS} = 1.5V, I_D = 3A$
Diode Forward Voltage	$V_{SD}$	_	0.7	1.2	V	$V_{GS} = 0V, I_S = 8.5A$
On State Drain Current (Note 9)	ID(ON)	20		_	Α	$V_{DS} \leq 5V$ , $V_{GS} = 4.5V$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C <sub>iss</sub>	_	2248	3372	pF	
Output Capacitance	Coss	_	295	443	pF	$V_{DS} = 10V, V_{GS} = 0V,$ -f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	265	398	pF	1 - 1.01/11/2
Gate Resistance	$R_g$	_	1.5	3	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	24	36	nC	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	56	84	nC	$V_{DS} = 10V$ , $I_{D} = 8.5A$
Gate-Source Charge	$Q_{gs}$	_	3.5	6	nC	V <sub>DS</sub> = 10V, I <sub>D</sub> = 8.5A
Gate-Drain Charge	$Q_{gd}$	_	5.1	8	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	_	3.6	6	ns	
Turn-On Rise Time	t <sub>r</sub>	_	2.6	4	ns	$V_{DS} = 10V, I_{D} = 8.5A$
Turn-Off Delay Time	t <sub>D(off)</sub>	_	21.6	33	ns	$V_{GS} = 4.5V, R_G = 1.8\Omega$
Turn-Off Fall Time	t <sub>f</sub>	_	13.5	21	ns	
Reverse Recovery Time	T <sub>rr</sub>	_	12.8	20	ns	I 0.54 4:/4+ 0404/
Reverse Recovery Charge	Q <sub>rr</sub>	_	6.9	11	nC	I <sub>F</sub> = 8.5A, di/dt = 210A/μs

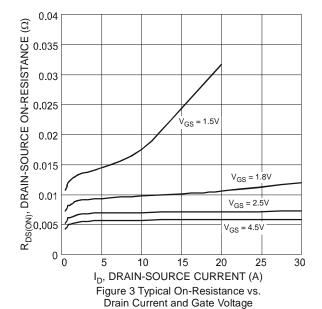
Notes:

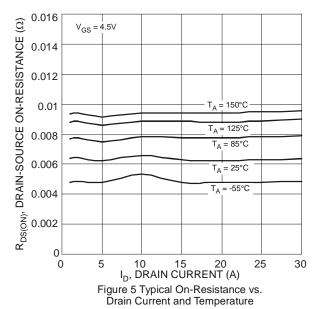
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7.  $I_{AS}$  and  $E_{AS}$  rating are based on low frequency and duty cycles to keep  $T_J$  = +25°C
- 8. Short duration pulse test used to minimize self-heating effect.
  9. Guaranteed by design. Not subject to product testing.











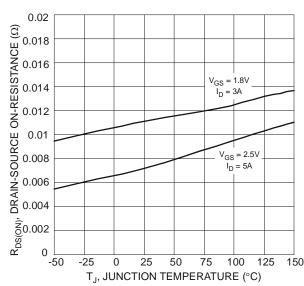
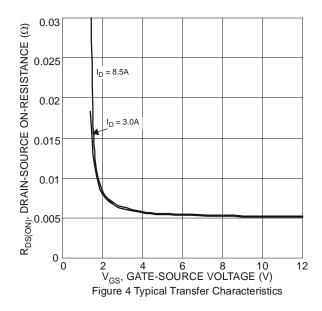
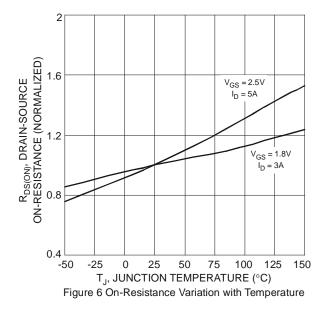


Figure 7 On-Resistance Variation with Temperature





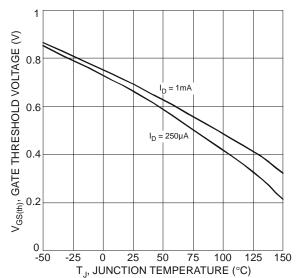
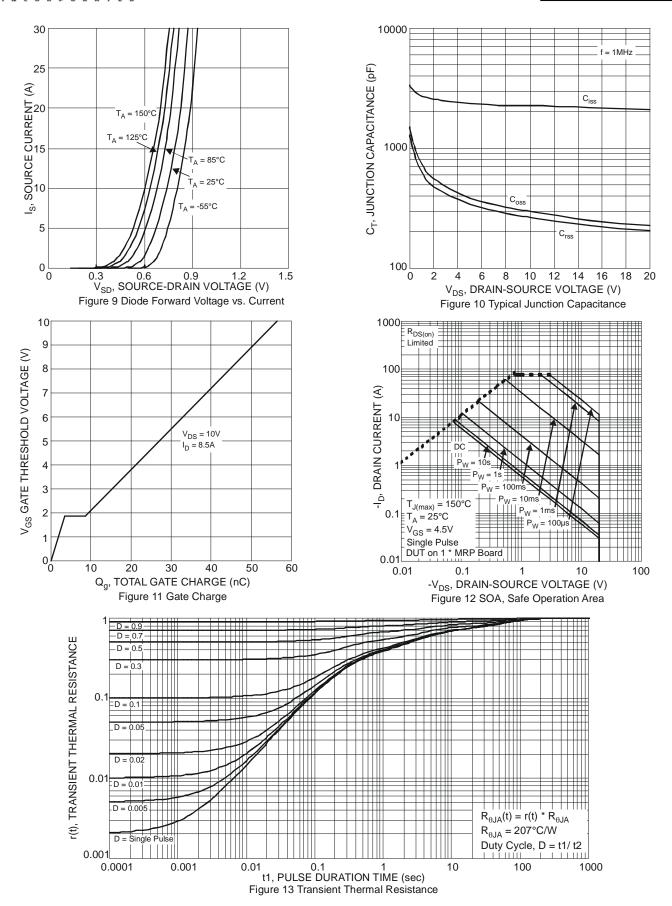


Figure 8 Gate Threshold Variation vs. Ambient Temperature

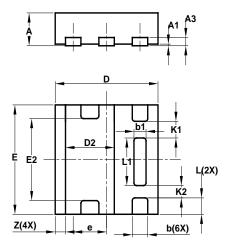






## **Package Outline Dimensions**

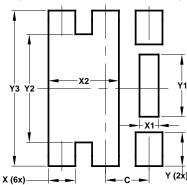
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



U-DFN2020-6								
Type E								
Dim	Min	Max	Тур					
Α	0.57	0.63	0.60					
A1	0	0.05	0.03					
A3		_	0.15					
b	0.25	0.35	0.30					
b1	0.185	0.285	0.235					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
Е	1.95	2.05	2.00					
E2	1.40	1.60	1.50					
е		_	0.65					
Г	0.25	0.35	0.30					
L1	0.82	0.92	0.87					
K1		_	0.305					
K2		_	0.225					
Z		_	0.20					
All Dimensions in mm								

## **Suggested Pad Layout**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



Dimensions	Value (in mm)
С	0.650
Х	0.400
X1	0.285
X2	1.050
Υ	0.500
Y1	0.920
Y2	1.600
Y3	2.300



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